

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>				
<b>Filing Date:</b>				
<b>Title of Invention:</b>	HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING METHOD AND APPARATUS			
<b>First Named Inventor:</b>	Masaru SHIRAI			
<b>Filer:</b>	Leslie J. Paperner/Ayako Asada			
<b>Attorney Docket Number:</b>	P30470			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
National Stage Fee	1631	1	300	300
Natl Stage Search Fee - Report provided	1642	1	400	400
National Stage Exam - all other cases	1633	1	200	200
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	1615	15	50	750
Independent claims in excess of 3	1614	1	200	200
<b>Miscellaneous-Filing:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1850</b>